

22 45. The semiconductor device package of claim 19/2 wherein at least one of the plurality of strips comprises a compliant carrier layer and at least one adhesive layer adhered to the compliant carrier layer.

46. A method for assembling a device package assembly for a semiconductor die, comprising adhering a semiconductor die having at least one conductive bond pad to a surface of an interposer having at least one conductive interconnect with a plurality of strips of compliant adhesive film.

47. The method of claim 46, further comprising injecting into regions remaining in between the semiconductor die and the interposer an encapsulating material.

48. The method of claim 46, further comprising bonding the electrically conductive interconnect to the bond pad.

49. The method of claim 46, further comprising coupling the electrically conductive interconnect to an external conductive terminal located on a surface of the interposer opposite of the surface on which the semiconductor die is adhered. --

REMARKS

Claims 1-18 and 38-49 are pending in the present application. Claims 1-18 have been presented for examination and new claims 38-49 have been added by amendment. Claims 1-7, 9-13, and 15-18 have been rejected under 35 U.S.C. 102(e) as being anticipated by U.S. Patent No. 5,852,326 to Khandros *et al.* ("Khandros"). Claims 8 and 14 have been rejected under 35 U.S.C. 103(a) as being unpatentable over to Khandros, in light of the Examiner taking judicial notice that solder balls are commonly used in the semiconductor industry for external terminals.

Embodiments of the present invention are directed to a semiconductor package assembly and method of assembly having a plurality of pieces of compliant and/or adhesive film